

**DOCKET NO. 01-C-084 (STMI01-01084)**  
**Customer No. 30425**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of : Harry Michael Siegel, et al.  
Serial No. : 10/066,245  
Filed : January 31, 2002  
For : METHOD FOR USING A PRE-FORMED FILM IN A TRANSFER  
MOLDING PROCESS FOR AN INTEGRATED CIRCUIT (AS  
AMENDED)  
Group No. : 1791  
Examiner : Edmund H. Lee  
Confirmation No. : 2782

**MAIL STOP AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**SECOND SUBSTITUTE AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION**

Applicant respectfully withdraws the Amendment and Response to Final Office Action filed March 17, 2008 and the Substitute Amendment and Response to Final Office Action filed July 3, 2008, and requests amendment the above-identified application as follows: